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FIIF Newsletter 3/2018

FIIF events during the fall of 2018

This fall’s first FIIF event (“**New trends in connectivity – How Narrow Band IoT and 5G will change the industry landscape**”) was held on September 20 at Marina Congress Center in Helsinki. The 60+ participants heard four excellent presentations from Juha Lyijynen (RD Velho Oy), Marko Lepola (Telia Oy), Matti Hellgren (IoT Forge), and Kimmo Kettunen (Nokia Oy).

You can find this event’s presentation materials by clicking the “**Partner log in**” label at the top right corner of FIIF’s web pages. **Access to this section is limited to FIIF members only**, so we ask you to give your e-mail address upon entering the page.

The next FIIF events will take place on:

> **Thursday, October 18, 2018** – FIIF event on “**IoT SW Platforms**” (Kampusareena, Korkeakoulunkatu 7, Tampere).
> Registration to this event is through the event web page.
>
> **Thursday, November 22, 2018** – FIIF event on “**Artificial Intelligence and Machine Learning**” (Capital region)
>
> **Thursday, December 13, 2018** – FIIF event on “**Cyber Security**” (Oulu)

Invitations to these events will be sent to the official FIIF contact persons, so **please make sure your company’s contacts in the FIIF mailing list are up to date!**

If in doubt, please contact the FIIF Manager (fiif.manager@dimecc.com).

Read more

Empirical Software Engineering International Week 2018 (October 8-12, 2018)

When	October 8-12, 2018
Where	Hotel Lasaretti (Kasarmintie 13, Oulu, Finland)
Cost	Event-specific **registration fees** for participants. Sponsorship packages for sponsors.
Contact	Prof. **Markku Oivo** (markku.oivo@oulu.fi) More information at: https://eseiw2018.wixsite.com/oulu

Empirical Software Engineering International Week 2018 (ESEIW 2018) collects around 200 software engineering professionals and researchers around the world. The special theme of the week is **empirical software engineering** focusing on experiments and research actions validated in practice.

The main conference during the week is the **12th ACM / IEEE International Symposium on Empirical Software Engineering and Measurement** (ESEM, http://eseiw2018.wixsite.com/esem2018). Other activities include:

- **ISERN** (International Software Engineering Research Network),
- **MEGSUS** (Measurement and Metrics for Green and Sustainable Software Systems),
- **IASESE** (International Advanced School on Empirical Software Engineering),
- **IDoESE** (International Doctoral Symposium on Empirical Software Engineering),
- **PROMISE'18** (International Conference on Predictive Models in Software Engineering),
- EMSE Erasmus Summer School, and
- Industry Day.

Sponsorship packages range from "Bronze" (€250) to "Platinum" (€2500) with increasing levels of visibility on materials and websites. For more information, please contact the General Chair, Prof essor **Markku Oivo** (markku.oivo@oulu.fi, tel. +358 40 8227702).

The 11th DIMECC Annual Seminar (October 24, 2018)

When	October 24, 2018, full-day event (9:00 – 16:30) + DIMECC Party
Where	Tapahtumakeskus Koskenranta (Katariina Saksilaisen katu 9, Helsinki, Finland)
Cost	**Free of charge**, but registration is required. Cancellations by October 15, 2018. No show fee of €150 € (+ VAT) for those participants, who register, but don't attend.
Contact	Event page. Registration link. Ms. **Doris Pryjma** (doris.pryjma@dimecc.com)

DIMECC 10 year anniversary seminar will bring together over 200 decision makers from companies (executives, operational directors, and R&D personnel), professors, teachers, and public sector innovation system experts. During the day a catering of the most impactful results from DIMECC programs over the years will be presented.

Come to hear how DIMECC programs have changed the business and delivered impact. The anniversary seminar will also offer interesting **keynotes** on how the digitalization will develop and towards what contents and actions digitalization efforts should be directed in the future.

CEO Forum, organized in collaboration with Technology Industries of Finland, will bring together a group of visionary leaders to discuss the success of future business.

In the evening you can enjoy the get-together dinner and **DIMECC ten-year anniversary party**!

Read more

DIMECC Demobooster Demoday (October 25, 2018)

When	October 25, 2018, full-day event (9:30 – 16:00) Note! Change of day!
Where	Morning session at Aalto university (Otakaari 1, Espoo, Finland), in the Nokia room Afternoon session at Aalto A Grid (Otakaari 5, Espoo, Finland)
Cost	Participation fee, which depends on the size of the company (from 500 €/micro to 6000 €/large, +VAT 24 % – covers two Demoday events)
Contact	For more information, please contact at Gaia Consulting Mr. **Lauri Larvus** (lauri.larvus@gaia.fi, tel. +358 50 3892703) and at DIMECC Ms. **Doris Pryjma** (doris.pryjma@dimecc.com, tel. +358 40 8408790) Demoday registration through this link.

DIMECC Demobooster (www.demobooster.fi) is an innovation service that brings efficiency to your R&D&I process in an agile and innovative manner. The service is a platform that matches the digital needs of companies from manufacturing, process and service industries (a.k.a. **Appliers**) with innovative solution-providers specialized in software and embedded solutions (a.k.a. **Producers**).

At Demoday, selected Applier companies present their specifications for a MVP (Minimum Viable Product) and the Producers pitch their implementation ideas and solution proposals. For more details regarding the overall Demobooster process, please see Demobooster facts.

During this Demobooster Demoday we will hear challenges from the following Appliers:

- Meyer Turku: **a flow simulation tool** (passengers, luggage, laundry etc.) for passenger ships.
- Granlund: **a feedback solution** to support user-centric buildings.
- Elenia: **a sensoring solution** for electricity network monitoring, more specifically for padmount transformers.

There is still room for 1-2 additional challenges from Appliers. Potential Appliers and Producers should contact Mr. Lauri Larvus at Gaia.

Note! Due to international guests from the DIGINNO research program, **this Demoday will be conducted in English**.

Read more

Future Factory 2018 (November 15, 2018)

When	November 15, 2018, full-day event (08:30 – 16:00)
Where	Sokos Hotel Torni (Ratapihankatu 43, Tampere, Finland)
Cost	**Free of charge**, but registration is required.
Contact	For more information and registration (only in Finnish): https://tapahtumat.almatalent.fi/tulevaisuuden-tehdas-2018 Note! All presentations and discussions will be in Finnish.


alma TALENT

Tulevaisuuden tehdas 2018

15.11.2018, Tampere

LUE LISÄÄ

tekniikka & talous

The “Future Factory 2018” –event offers insights into the future of factories and industrial production. This annual event, organized by Alma Talent, gathers together 150 decision makers in charge of industrial operations to discuss and debate the most current themes in the field.

This year’s key themes include:

- How should we respond to the upcoming **changes and challenges**?

- How to make factories an attractive workplace for the **younger generations**?

- What **competences** are needed in future factories and how can these competences be organized?

- Will industrial work transform into **knowledge work**?

- Can safety be a driver for a culture of **continuous improvement**?

- Will **Artificial Intelligence** bring added value to factories and how should we utilize it?

The event will provide you with answers to these questions. In addition, you will hear case examples about flexible production, automation, and energy efficiency.

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DIGINNO
Digital Innovation Network

Interreg
Baltic Sea Region

EUROPEAN UNION
EUROPEAN REGIONAL DEVELOPMENT FUND

Call to Action: DIGINNO – Business Needs Assessment

The DIGINNO program builds a unique network for innovative solutions in public-private co-operation to speed up the process towards the **Baltic Sea Region digital single market**. DIGINNO aims to increase innovation capacity of industrial SMEs, ICT associations, industry associations and public authorities in the area of industry digitalization. As part of this work the participants are conducting a joint Business Needs Assessment in the participating countries during the fall of 2018.

The purpose of this assessment is to get an **overview of the level of ICT usage** in industry, including the state of the art of Industry 4.0 digitalization. It will also help to **identify drivers/barriers** in the development and to provide **input for a further dialogue** with the EU policy makers. The main focus of this survey is in the Mechanical Manufacturing industry, but also companies from other industries are welcome to participate.

If you are interested in participating in this assessment, **please fill in the online web survey here**. The survey has 10 questions and its completion takes about 10-15 minutes. We will also conduct more in-depth interviews (45-60 minutes) with selected companies. In case you want to participate in this survey also through an interview, please leave your contact information at the end of the survey or contact Project Manager Risto Lehtinen (risto.lehtinen@dimecc.com, tel. +358 50 5553900).

Call to Action: China-Finland Digital Factory with Industry Internet (CFDFII)

As part of the **on-going China-Finland scientific co-operation**, Chinese companies are seeking Finnish partners for a wide variety of technologies and solutions, like IoT platform and systems, big data acquisition and analytics, sensor solutions, energy management, as well as transmission and network communication protocols (low-power, low-latency, high-bandwidth, high-reliability, wide-coverage).

Case 1: (by INDICS and University of Oulu) Digital factory for **electrical connectors, relays, optoelectronics and cable assemblies**. Challenges include:

- high degree of customization, high development costs, and long delivery cycle,
- need for higher assembly efficiency, completion and punctuality rate,
- predictability of product quality
- after sales traceability of products
- coordination of outsourcing
- processing of big data

Case 2: (by INDICS and University of Oulu) Digital factory for **automobile parts**. Challenges include:

- stamping die: too long assembly adjustment period (very heavy), too high repair rate for parts,
- CNC machine: low operational efficiency and utilization rate, too high energy consumption, unstable machining accuracy, unpredictable product quality

Case 3: (Victory Precision) Digital factory for **mechanical parts for the electronics industry**. Challenges include:

- reconfiguration of the automated production line,
- inaccuracy of production capacity measurement,
- production line (re)configuration,
- inaccurate production planning

The aim is to prepare **joint projects for the next SinoFinnish call**, where Finnish partners can apply funding from Business Finland. The call is planned to be opened in September-October 2018. Detailed schedule will be informed later.

For more information about the joint call and the above listed cases, please contact: Mr. **Matti Kinnunen** (matti.kinnunen@oulu.fi, tel. +358 29 4487686).

Call to Action: Next round for PoDoCo grants still open

Does your company have cutting-edge renewal ideas which could be further developed and investigated by a talented postdoc? The PoDoCo program may be just right for you!

PoDoCo (Post Docs in Companies, https://www.podoco.fi/) is a **matchmaking program** supporting long term competitiveness and strategic renewal of companies as well as employment of young doctors in the private sector. For companies, PoDoCo program offers an **opportunity to investigate new strategic openings** with the help of talented postdocs. The program will assist companies by:

- providing a channel for finding the right, highly-skilled and talented young postdocs, and
- offering a research grant that covers the costs of a postdoc during the research period.

The PoDoCo fall 2018 application round **closes on October 31, 2018**. For more information about the program and the fall application round, please visit the PoDoCo website.

Read more

Call to Action: Industrial partners are welcome to join DIMECC's PROXY program

DIMECC continues its activities in advancing the **usage of Virtual Reality (VR) and Augmented Reality (AR) technologies in the Finnish industry**. In the preparation is a new joint program called PROXY, which focuses in value creation in the areas of:

- Product visualization and interaction,
- Real-time collaboration and remote service,
- Workflow guidance, and
- Disruptive product features.

For further information about the PROXY program, please contact **Arto Peltomaa** (e-mail arto.peltomaa@dimecc.com, tel. +358 40 5511434).

Call to Action: Innovation Challenge to find future steel product fingerprint (submission deadline November 2, 2018)

SSAB and Sandvik Materials Technology are joining forces to find the best ideas on how to track steel products during their whole life cycle.

Is it digital, does it use Artificial Intelligence, is it a chemical solution, or could it be mechanics? Companies and research groups of all sizes are welcome to participate, and the winner will get the chance to develop the idea further in a long-term partnership with SSAB and Sandvik Materials Technology, with access to vast business knowledge and international customer networks. The challenge is part of the **SmartSteel project** related to PiiA, Process Industrial IT and Automation, a Swedish strategic innovation program financed by **Vinnova**, the **Swedish Energy Agency** and **Formas**.

This challenge is organized by **Spinverse**, a firm specialized in driving open innovation ecosystems and turning radical innovations to business. Proposals are submitted via a web tool.

Those planning to submit their proposals should take into account that:

- The solution needs to work in heavy industry environment.
- Product identifier may change during any stage, but changes need to be tracked.
- Product identifier should follow the pieces, even after slitting and cutting of the mother piece.
- Possible product identifier device should cost less than 10 k€ in the final form.
- Methods based on radioactive signatures will not be considered (safety and contamination issues).
- Method should not impose health hazards on humans and not harm the environment.

Submission of proposals is open until November 2, 2018 (23:00 CET). Finalists will be selected by November 12, 2018, and the Pitching Day will be organized in Stockholm, Sweden on **December 12, 2018**.

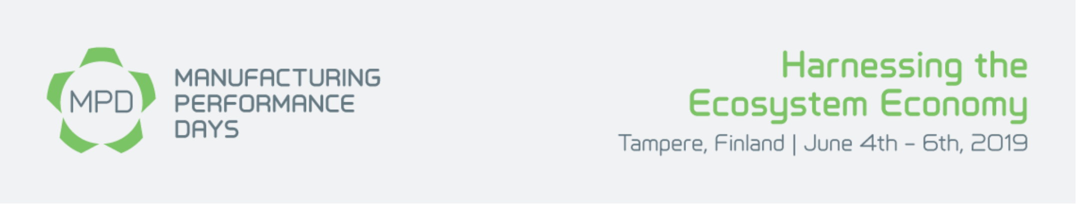
For more information on how to participate, and about the parties organizing this challenge, please check the call letter and/or SSAB's press release.

"Knights of #SLUSH" – VIP Investor Event (December 2018)

SLUSH 2018 will be organized during December 4-5, 2018 in Helsinki, Finland. At the same time, but not as part of the official SLUSH program, there will also be a **special VIP event for selected international investors from China, Singapore and USA**, who are looking for investment opportunities in Finland, especially **growth-oriented, internationally-focused SMEs** with proven solutions in the areas of **health care**, **manufacturing**, and **ocean technologies**.

If you are interested in getting more information about this pitching opportunity, please contact the FIIF Manager (fiif.manager@dimecc.com).

Sneak peek to 2019 events



When	June 4-6, 2019
Where	Tähtiareena at Tampere Exhibition and Sports Centre (Ilmailunkatu 20, Tampere, Finland)
Cost	**Free** for visitors (by invitation only) **Partner packages** for exhibitors
Contact	Event info for visitors: http://www.mpdays.com/

MPD 2019 is an **international top level B2B summit** for manufacturing industries, researchers, and technology and service providers worldwide. This event will bring together internationally recognized experts and academia to discuss and represent industrial best practices and operational excellence, novel business concepts, as well as scientific and technological breakthroughs in the field.

Partner packages range from “Standard” (€5k + VAT) to “Premium” (€17k + VAT) and to “Strategic” (€25k + VAT). Startup booths have a dedicated area (about €1k + VAT). More than half of the event partnerships are already sold (Beckhoff, DIMECC, Fastems, Siemens, Technology Industries of Finland, Tampere University of technology, VTT and Wapice). The first invitations to guests will be sent out early November.

For more information about the event and tailored partner packages, please contact DIMECC CEO Harri Kulmala (email harri.kulmala@dimecc.com, tel. +358 40 8406380).

Glass Performance Days (June 2019)

When	June 25-28, 2019
Where	Tampere, Finland
Cost	**Free** for visitors, **partner packages** for exhibitors
Contact	More information at https://gpd.fi/

Technical sessions and workshops will address the **challenges the industry faces today** regarding the ever-changing demands on city planning, building design, energy-efficiency and environmental fit. A special focus will be on the **contribution of new glass technologies** to these demands. There will also be the world’s first **glass industry startup event**.

Comments from FIIF Manager

The next FIIF Newsletter will be published in November 2018. If you have topics which you would like to bring to the attention of all FIIF members, please contact the FIIF Manager.

FIIF Manager also maintains the **FIIF mailing list**, which is used to distribute information to contact persons – including but not limited to the FIIF Newsletter and invitations to specific FIIF events. Please contact the FIIF Manager regarding any changes to the FIIF mailing list.

Greetings, and have a nice and sunny fall!

Risto Lehtinen
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fiif.manager@dimecc.com

FIIF on Twitter

P.S. Did you know that you can follow FIIF also in Twitter (**@FIIF_catalyst**)?
Re-tweets are highly appreciated!

Summary of upcoming FIIF events (save the date!)

Name	Date	Location
FIIF event on ”IoT SW Platforms"	Oct 18	Tampere
FIIF event on “Artificial Intelligence and Machine Learning”	Nov 22	Capital region
FIIF event on “Cyber Security”	Dec 13	Oulu

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